

**Doubler** Rev. V1 13.5-17.0/27.0-34.0 GHz Mimix Broadband

#### **Features**

- Integrated Gain, Doubler and Driver Stages
- Self-biased Architecture
- +21.0 dBm Output Saturated Power
- 40.0 dBc Fundamental Suppression
- On-Chip ESD Protection
- 100% On-Wafer RF, DC & Output Power Testing
- 100% Visual Inspection to MIL-STD-883 Method 2010
- RoHS\* Compliant and 260°C Reflow Compatible

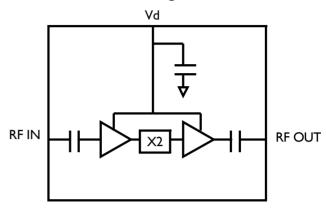
#### **Description**

M/A-COM Tech's 13.5-17.0 / 27.0-34.0 GHz GaAs MMIC doubler integrates a gain stage, passive doubler and driver amplifier onto a single device. The XX1007-BD has a self-biased architecture requiring a single positive supply (+5V) only and integrated on-chip bypassing capacitor eliminating the need for external capacitor. This MMIC uses M/A Tech's GaAs PHEMT device model technology, and is based upon electron beam lithography to ensure high repeatability and uniformity. The chip has integrated ESD structures for protection and surface passivation to protect and provide a rugged part with backside via holes and gold metallization to allow either a conductive epoxy or eutectic solder die attach process. This device is well suited for Millimeter wave Point-to-Point Radio. LMDS, SATCOM and VSAT applications.

#### **Ordering Information**

Part Number	Package
XX1007-BD-000V	"V" - vacuum release gel paks
XX1007-BD-EV1	evaluation module

### **Functional Block Diagram**



### **Absolute Maximum Ratings**

Parameter	Absolute Max.			
Supply Voltage (Vd)	+6.0 VDC			
Supply Current (Id)	300 mA			
Gate Bias Voltage (Vg)	+0.3 VDC			
Input Power (RF Pin)	TBD			
Storage Temperature (Tstg)	-65 to +165 °C			
Operating Temperature (Ta)	-55 to MTTF Table <sup>1</sup>			
Channel Temperature (Tch)	MTTF Table <sup>1</sup>			

Channel temperature directly affects a device's MTTF. It is recommended to keep channel temperature as low as possible to maximize

Commitment to produce in volume is not guaranteed.

<sup>•</sup> India Tel: +91.80.43537383 Visit www.macomtech.com for additional data sheets and product information.



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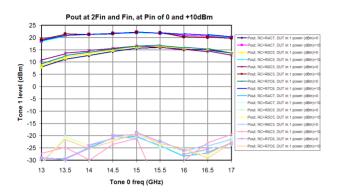
## Electrical Specifications: 13.5-17 GHz (fin) (Ambient Temperature T = 25°C)

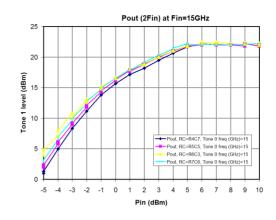
Parameter	Units	Min.	Тур.	Max.
Output Frequency Range (fout)	GHz	27.0	-	34.0
Input Return Loss (S11)	dB -		-8.0	-
Output Return Loss (S22)	dB	-	-10.0	-
Fundamental Level at the Output	dBc	-28.0	-35.0	-
RF Input Power (RF Pin)	dBm	-	+8.0	-
Output Power at 8.0 dBm Pin (Pout)	dBm	+16.0	+21.0	-
Drain Bias Voltage (Vd)	VDC	-	+5.0	+5.5
Supply Current (ld1,2,3) (Vd=5.0V Typical)	mA	-	200	240

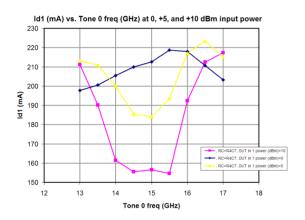


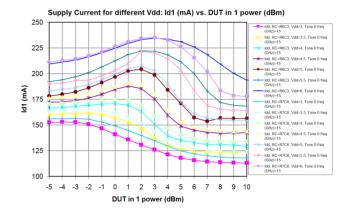
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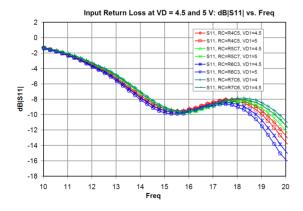
### **Typical Performance Curves**

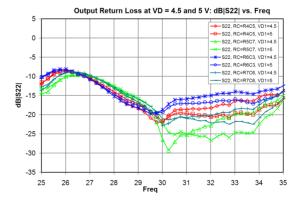










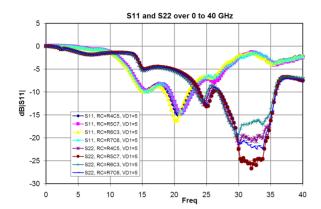


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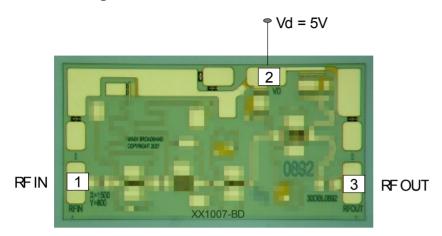
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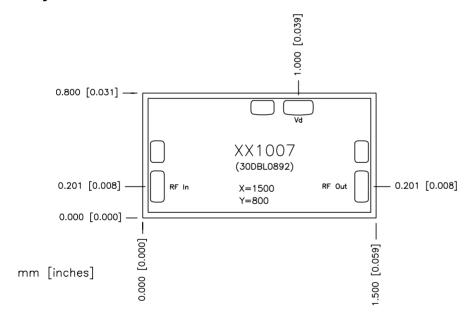
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### **Bias Arrangement**



## **Physical Dimensions**



typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.



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### MTTF Tables (TBD)

These numbers were calculated based on accelerated life test information and thermal model analysis received from the fabricating foundry.

Backplate Temperature	Channel Temperature	Rth	MTTF Hours	FITs
55 deg Celsius	deg Celsius	C/W	E+	E+
75 deg Celsius	deg Celsius	C/W	E+	E+
95 deg Celsius	deg Celsius	C/W	E+	E+

Bias Conditions: Vd=5.0V, Id=200mA

### **Handling Procedures**

Please observe the following precautions to avoid damage:

## **Static Sensitivity**

Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these class 2 devices.

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